



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Blaine J. Thurgood

Serial No.: 10/787,351

Filed: February 26, 2004

For: SEMICONDUCTOR DIE
CONFIGURED FOR USE WITH
INTERPOSER SUBSTRATES HAVING
REINFORCED INTERCONNECT SLOTS

Confirmation No.: 4866

Examiner: J. Clark

Group Art Unit: 2815

Attorney Docket No.: 2269-5520.2US
(02-0676.02/US)

Notice of Allowance Mailed:

January 6, 2006

NOTICE OF EXPRESS MAILING

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Person making Deposit: Timothy Palfreyman

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 3 of this paper;

Amendments to the Abstract appear on page 12 of this paper;

Amendments to the claims are set forth in the listing of the claims that begins on page 13 of this paper;

Corrections to the drawings are summarized on page 15 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

Remarks start at page 16 of this paper.